

# d'Holoscope

Full field real time lensless 3D imaging system for MEMS and  
Microsystem testing and inspection



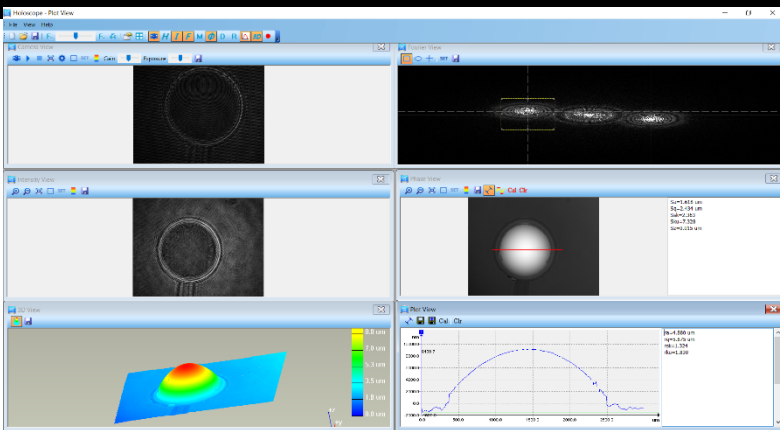
Parameters	Specifications
Sample surface	Specular
Image types	Intensity , Quantitative Phase, 3D Profile
Image Sensor	1/3", 1280X960 pixels 8 bit 3.75 x3.75um pixel
Fiber coupled Laser	660nm – other wavelengths available
Magnification	2.97X
Axial Resolution	10 nm
Lateral Resolution	7.5 um
Field of View	4mm by 3mm
Size and Weight	LXWXH: 120X42X62cm&460g

**d'optrotron**  
Dynamic vision of new Dimensions

[www.doptron.com](http://www.doptron.com)

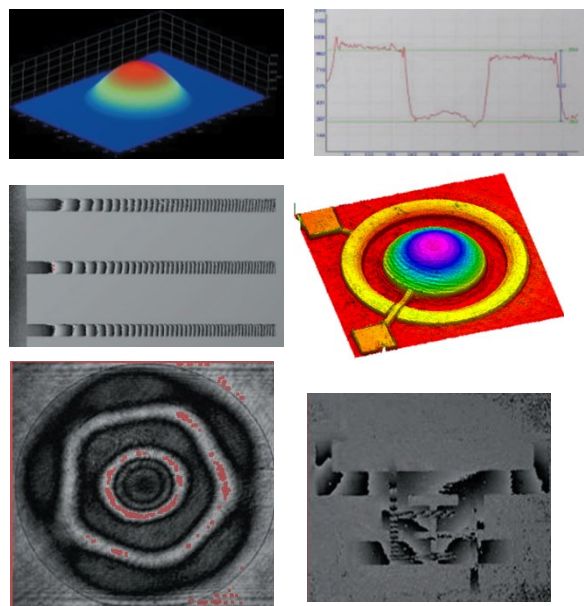
[sales@doptron.com](mailto:sales@doptron.com)

# Software Features



- User-friendly
- Real-life capture
- Quantitative phase analysis, line profile analysis, color maps
- 3D plot of sample and height/depth analysis
- Fully customizable

## Applications



### MEMS Microsystem Characterization

- 3D Inspection
- Static and dynamic characterization
- On line process monitoring
- Surface roughness Measurement

### Characterization of Si Wafers

- Warpage measurement
- Defect Analysis
- Non-destructive testing and inspection

### Micro-mechanics

- Static and dynamic deformation analysis
- Residual Stress Measurement
- Micromechanics design and characterization

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